Electronics and Data Processing

Importance and motivation

- Readout electronics and data processing systems are fundamental enablers for all HEP experiments
- Next generations of detectors will pose extreme challenges for electronics
 - Arguable that for several future projects, this is *the* key R&D problem
- Growing issues in accessing / using state-of-the-art industrial technology
 - The approach we took for LHC experiments will not work in the coming decades

Requirements from experiments

- Finer granularity, more channels, more precision in readout
 - Often driven by inclusion of timing information
- Lower power dissipation, less material
- Close coupling of readout ASICs to sensors
- Ultra-high radiation hardness (in some cases) and exceptional reliability
- Zero suppression and data processing on the detector
- Why start now?
 - Timeline for LHC developments shows R&D for next detectors should start now
 - For further generations, basic R&D is needed to demonstrate plausibility and fully test novel new approaches



Summary of R&D Themes

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		DRDT		< 2030			2030-203	5	2035- 2040	20	40-2045	> 20	145
Data density	High data rate ASICs and systems	7.1		•			*						
	New link technologies (fibre, wireless, wireline)	7.1	۲	•									
	Power and readout efficiency	7.1		•			*						
Intelligence on the detector	Front-end programmability, modularity and configurability	7.2											
	Intelligent power management	7.2					*						
	Advanced data reduction techniques (ML/AI)	7.2											
4D- techniques	High-performance sampling (TDCs, ADCs)	7.3		•									
	High precision timing distribution	7.3				Ó							
	Novel on-chip architectures	7.3		•		Ŏ Ì				Ŏ			Ŏ
Extreme environments and longevity	Radiation hardness	7.4		• •)	ŎÌ							
	Cryogenic temperatures	7.4			•							Ŏ	
	Reliability, fault tolerance, detector control	7.4		•									
	Cooling	7.4					*		•) 🍈 (
Emerging technologies	Novel microelectronic technologies, devices, materials	7.5		•		ÕÌ			•				Ŏ
	Silicon photonics	7.5							ŎŎ	Ŏ			Ŏ
	3D-integration and high-density interconnects	7.5					*			Ŏ			Ŏ
	Keeping pace with, adapting and interfacing to COTS	7.5				ŏ				Ŏ			

* LHCb Velo

Next Steps

- Clear motivations to proceed with R&D programme
 - Noting that funding for R&D is in tension with experiment projects
 - This will be a ramp-up process over the next few years
- There is a vibrant and active expert community across Europe
 - As evidenced by several hundred participants in the roadmap process
 - Deep expertise in all areas but can it be maintained?
- Discussions of RD organisation will begin later in 2022
 - Strand A (2022): ensuring support and facilities for current developments and near-term R&D
 - Explicit cooperation between labs and institutes to provide access to latest process and tools
 - Strand B (2023): prioritisation and organisation of R&D work
 - Collaboration structure likely to be based on the R&D Themes already identified
 - Many opportunities for participation and leadership from the community
- Questions? Comments?
 - Contacts: <u>dave.newbold@cern.ch</u> or <u>francois.vasey@cern.ch</u>

Relevance to FCC in the UK

- New RD collaborations look likely to proceed
 - It would be strange indeed for the UK to have no participation in this...
 - Indeed I would claim that electronics / DAQ is an area we can continue to lead
 - One therefore assumes that money will be found within the programme
- Large overlap with UK expertise / interest in e+e-
 - Design and development of tracking system readout
 - Back-end DAQ and computing; triggering and data processing
 - Development of next-generation fully 4D / 5D detectors
- Situation in STFC (with a TF7 hat on)
 - PPTAP has finished and reported to TAAB / Executive Board
 - Clear recommendation to complement recent commitment on blue skies R&D with a corresponding programme of 'structured R&D'
 - We will see what happens in the coming year or so
- My view
 - The 'future e+e- detector' programme has to incorporate both 'generic' R&D and facility-specific studies on physics and experiments
 - Don't expect a revolution overnight, but we do need to be in at the start and leading

Additional Slides



Roadmap Process and Structure

Three main topics

- Front-end ASICs; Links, powering and interconnects; Back-end systems
- Review of the state-of-the-art in each area
- Examination of the main challenges for future projects
- Process and inputs
 - Experiment workshop defined the key technical challenges
 - Community workshop provided input on current and proposed R&D
 - Also the views of the community on prioritisation and working practices
 - A (detailed) survey of the community indicated broad agreement on the main challenges and opportunities
 - Panel of six experts constructed the final roadmap recommendations
- Final output
 - Development of five R&D 'work packages' with several areas each
 - Recommendations on working practices and collaboration
 - Input to the general recommendations of the overall roadmap

R&D Themes

- Data density
 - Dealing with the vastly increased channel count and data per channel
 - Requires work in on-detector processing, link technologies and power efficiency
- Intelligence on the detector
 - Advanced (incl. ML) data reduction techniques at the front end, and the technologies to enable this
- 4D techniques
 - Enabling and using 4D detector information for data reduction, triggering and reconstruction
- Extreme environments
 - Radiation; cryogenic conditions; reliability and robust controls
- Emerging technologies
 - New materials, devices and signalling methods
 - Interoperability with the industrial / commercial standards of the future
- Note that these challenges span the entire spectrum of HEP
 - Not just about collider experiments; significant challenges in neutrino, low-background and quantum detectors also



General Recommendations

- Novel developments vs 'structured R&D'
 - Clearly need both! But realistically, blue-skies work still depends on excellent labs and tools...
- Software and firmware
 - Electronics is not just about hardware
 - Many key development challenges in sw /fw (and verification)
- Collaborative model
 - Obvious need to avoid parallel and duplicate efforts; but allow contributions from the widest pool
 - Discussion of the 'hub and spoke' model facilitating intellectual input from all
- Demonstrators and common developments
 - Most electronics challenges are 'systems issues'; need to build demonstrator systems not necessarily focussed on specific experiments
 - Clear need for standardisation, sharing of IP, and common developments
 - Avoiding the tens-of-similar-projects issues seen on LHC
- Infrastructure
 - Support via tools, IP, engineering expertise, specialised labs, irradiation facilities, etc...
 - Traditionally provided via the major European labs
- Interaction with industry
 - Essential to track industry developments, and maintain access to cutting-edge technologies
 - Some things industry will simply not do for us, however...

